A SEMICONDUCTOR PACKAGE AND A METHOD FOR FORMING SAME

Abstract of the Invention

Gold studs (9) are bonded to bond pads (7) of a semiconductor wafer (12). A layer of epoxy (11) is formed on the semiconductor wafer leaving the upper portions of the gold studs (9) exposed. A patterned layer on the layer of epoxy (11) has solder locations (13) and runners (14) that connect the solder locations to the bond pads (7) via the gold studs (9). Solder spheres (15) can be disposed at the solder locations (13). The dies of the semiconductor wafer (12) can be tested prior to singulation, and the resultant packaged die can be conveniently handled.

(Figures 5 and 6 accompany this abstract)